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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HYOUNG HO KO	10/28/2014
JONG PAL KIM	11/03/2014
TAK HYUNG LEE	11/03/2014

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU, GYEONGGI-DO, 443-742
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State/Country:	KOREA, REPUBLIC OF
Name:	THE INDUSTRY & ACADEMIC COOPERATION IN CHUNGNAM NATIONAL UNIVERSITY (IAC)
Street Address:	99, DAEHAK-RO, YUSEONG-GU
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State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14600670

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 012052.0857

NAME OF SUBMITTER: LOREN H. TUNG

SIGNATURE: /Loren H. Tung/

DATE SIGNED: 01/20/2015

PATENT REEL: 034760 FRAME: 0713

Total Attachments: 4

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PATENT REEL: 034760 FRAME: 0714

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

As a below-named inventor, I hereby declare that this de-	claration is directed to the application attached hereto, or
to United States Application Number or PCT International	Application Number 14/600,670
filed on January 20, 2015 (if applicable), er	rtitled:

APPARATUS AND METHOD OF MEASURING BIO IMPEDANCE

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

Samsung Electronics Co., Ltd. 129, Samsung-ro, Yeongtong-gu Suwon-si, Gyeonggi-do, 443-742 Republic of Korea

The Industry & Academic Cooperation in Chungnam National University (IAC) 99, Daehak-ro, Yuseong-gu

Daejeon, 305-764 Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number

14/600,670 filed on <u>January 20, 2015</u>	14/600,670	filed on	January	- Z U ,	ZUID
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I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation

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COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and Inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	KO, Hyoung Ho
Inventor's Signature	Av 11 july 60 Date 28 1/6 12014
Residence (City, Country)	Daejeon, Republic of Korea
Mailing Address	99, Daehak-ro, Yuseong-gu Daejeon, 305-764 Republic of Korea
Inventor's Legal Name	KIM, Jong Pal
Inventor's Signature	Date / /2014
Residence (City, Country)	Seoul, Republic of Korea
Mailing Address	c/o Samsung Advanced institute of Technology 130, Samsung-ro ,Yeongtong-gu Suwon-si, Gyeonggi-do, 443-803 Republic of Korea .

inventor's Legal Name	LEE, Tak Hyung
Inventor's Signature	Date / /2014
Residence (City, Country)	Suwon-si, Republic of Korea
Mailing Address	c/o Samsung Advanced Institute of Technology 130, Samsung-ro ,Yeongtong-gu Suwon-si, Gyeonggi-do, 443-803 Republic of Korea

COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

DECLARATION

As a below-named inventor, I f	hereby declare that this declaration is directed to the a	application attached hereto, or
to United States Application Nu	umber or PCT International Application Number	14/600,670
filed on January 20, 2	015 (if applicable), entitled:	

APPARATUS AND METHOD OF MEASURING BIO IMPEDANCE

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

ASSIGNMENT

For valuable consideration, I, as a below-named assignor, hereby assign to:

Samsung Electronics Co., Ltd. 129, Samsung-ro, Yeongtong-gu Suwon-si, Gyeonggi-do, 443-742 Republic of Korea

The Industry & Academic Cooperation in Chungnam National University (IAC) 99, Daehak-ro, Yuseong-gu Daejeon, 305-764 Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number

14/600,670	filed on	January	20,	2015	J
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I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation

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COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)

Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	KO, Hyoung Ho			***************************************	***************************************
Inventor's Signature		Date	1	/2014	
Residence (City, Country)	Daejeon, Republic of Korea	J	L		
Mailing Address	99, Daehak-ro, Yuseong-gu Daejeon, 305-764 Republic of Korea				***************************************

Inventor's Legal Name	KiM, Jong Pal	***************************************	***************************************
inventor's Signature	1 To Wh	Date	NoV/ 3 /2014
Residence (City, Country)	Seoul, Republic of Korea		
Malling Address	c/o Samsung Advanced Institute of Technology 130, Samsung-ro ,Yeongtong-gu Suwon-si, Gyeonggi-do, 443-803 Republic of Korea		

Inventor's Legal Name	LEE, Tak Hyung	***************************************	***************************************
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